SP	FC	IFI	CA ₁	NS
JE				110

CUSTOMER . CJP083

SAMPLE CODE . SG12032LRS-DGB-H-Q

MASS PRODUCTION CODE . PG12032LRS-DGB-H-Q

SAMPLE VERSION . 01

SPECIFICATIONS EDITION . 001

DRAWING NO. (Ver.) : JLMD- PG12032LRS-DGB-H-Q_001

PACKAGING NO. (Ver.) : JPKG- PG12032LRS-DGB-H-Q_001

Customer Approved

Date:

Approved	Checked	Designer
 	劉進	徐明菲

- □ Preliminary specification for design input
- Specification for sample approval

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RECORDS OF REVISION

Date (mm / dd / yyyy)	Ver	Edi	Description	Page	Design by
2006/6/15	0		Revised Contents		
2006/11/15	Α		Update 2.2 Interface Pin Description		
2018/07/09	01	001	Update Specification (Client required the specification of HD's edition)	-	徐明菲

Total: 30 page



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Appendix: 1. LCM Drawing

2. Packing Specification

Note: for detailed information please refer to IC data sheet: SBN1661G-M18-D



1. SPECIFICATIONS

1.1 Features

Item	Standard Value				
Display Type	120*32 Dots				
LCD Type	STN, Gray, Transflective, Positive, Extended Temp.				
Driver Condition	LCD Module: 1/32 Duty , 1/5 Bias				
Viewing Direction	6 O'clock				
Weight	25.6 g				
Interface	8-bits parallel data bus				
Other (controller / driver IC)	SBN1661G-M18-D				
	THIS PRODUCT CONFORMS THE ROHS OF PTC				
ROHS	Detail information please refer web site :				
	http://www.powertip.com.tw/news.php?area_id_view=1085560481/				

1.2 Mechanical Specifications

Item	Standard Value				
Outline Dimension	68.1 (L) *38.9 (w) * 7.6(H)				
Viewing Area	62.0(L) * 22.5(w)	mm			
Active Area	56.35(L) * 20.75 (w)	mm			
Dot Size	0.42 (L) * 0.60(w)	mm			
Dot Pitch	0.47 (L) * 0.65 (w)	mm			

Note: For detailed information please refer to LCM drawing

1.3 Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply Voltage	V _{DD}	-	-0.3	7.0	V
LCD Driver Supply Voltage	VLCD	-	0	13	V
Input Voltage	Vin	-	-0.3	VDD+0.3	V
Operating Temperature	Тор	-	-20	70	$^{\circ}\! C$
Storage Temperature	Tst	-	-30	80	$^{\circ}\!\mathbb{C}$
Storage Humidity	H _D	Ta<60 °C	-	90	%RH



1.4 DC Electrical Characteristics

 V_{DD} =5.0 V \pm 0.5V , V_{SS} = 0V , Ta = 25 $^{\circ}\text{C}$

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Logic Supply Voltage	V _{DD}	-	4.5	5.0	5.5	V
"H" Input Voltage	VIH	-	VDD-2.2	-	VDD	V
"L" Input Voltage	VIL	-	0	-	0.8	V
"H" Output Voltage	VoH	I _{OH} =-2.0mA	VDD-0.3	-	VDD	V
"L" Output Voltage	V _{OL}	I _{OL} =2.0mA	0	-	0.3	V
Supply Current	l _{DD}	V _{DD} =5.0V;V _{OP} =6.0V;	-	80	120	mA
		-20 ℃	-	-	-	
LCM Driver Voltage	Vop*1	25 ℃	5.8	6.0	6.2	V
		70℃	-	-	-	

NOTE: *1 The VOP test point is VDD-VO.





1.5 Optical Characteristics

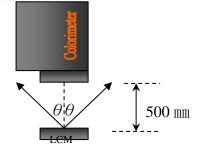
LCD Panel : 1/32Duty \cdot 1/5Bias \cdot $V_{OP} = 5.8$ V \cdot Ta = 25°C

Item		Symbol	Conditions	Min.	Тур.	Max.	Unit	Reference
Response Time	Rise	tr		-	90	135	ms	Note2
Response fille	Fall	tf	_	-	180	270		Notez
	Тор	θΥ+		30	- 4	-		
Viewing angle	Bottom	θΥ-	0>0.0	30		-	-	Notes 1
range	Left	θX-	C>2.0	35	/-	-	Deg.	Notes 1
	Right	θX+		35	(-	-		
Contrast Ra	tio	С	θ = 0°	-	3	-	-	Note 3
Average Bright (LCD & BL)		IV		5	9	-	cd/m2	
Wavelengt (without LCD		λр	IF=100mA	569	572	576	nm	Note 4
Uniformity '	'1	△В		70	-	-	%	

Note 4

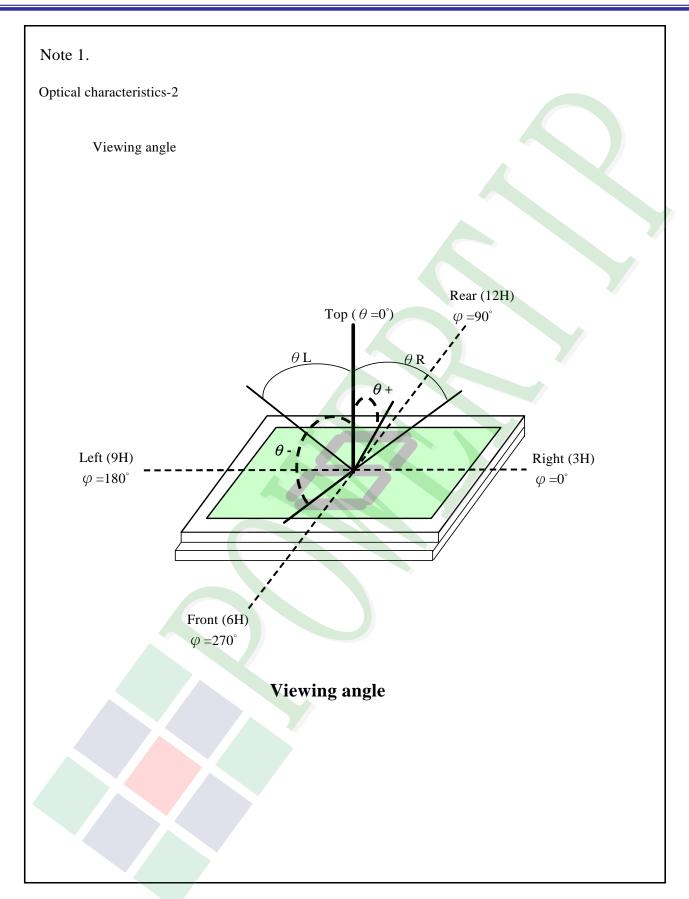
- 1 : △B=B(min) / B(max) * 100%
- 2 : Measurement Condition for Optical Characteristics:
 - a : Environment: 25°C±5°C / 60±20%R.H → no wind → dark room below 10 Lux at typical lamp current and typical operating frequency.
 - b : Measurement Distance: $500 \pm 50 \text{ mm}$, $(\theta = 0^{\circ})$
 - c: Equipment: TOPCON BM-7 fast, (field 1°), after 10 minutes operation.
 - d: The uncertainty of the C.I.E coordinate measurement ±0.01, Average Brightness ± 4%



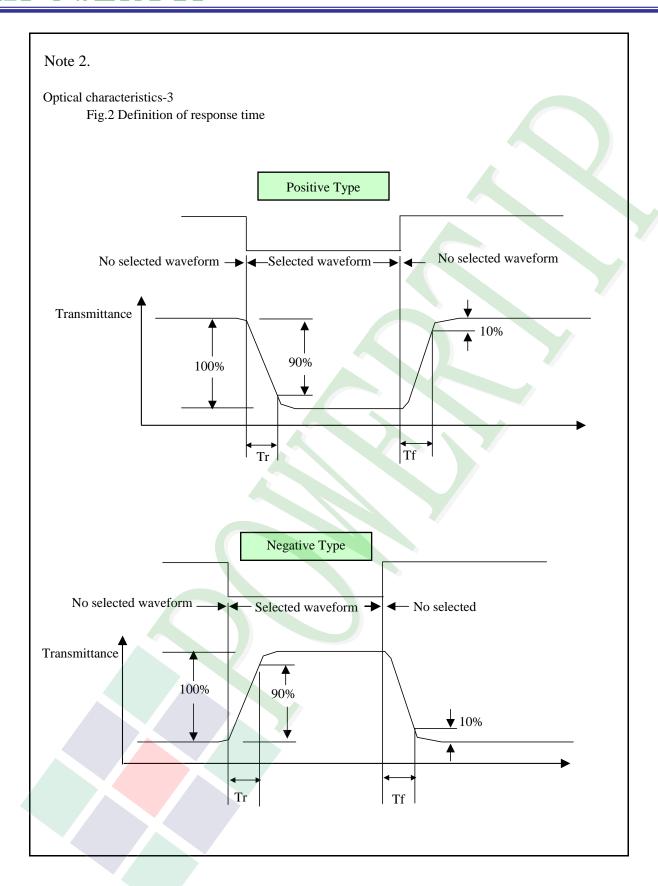


Colorimeter=BM-7 fast









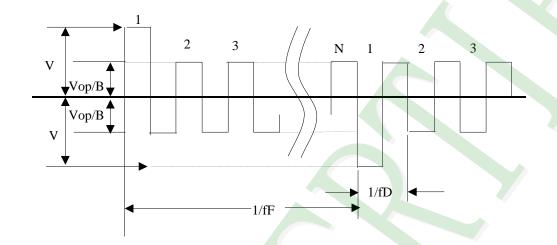


Electrical characteristics-2

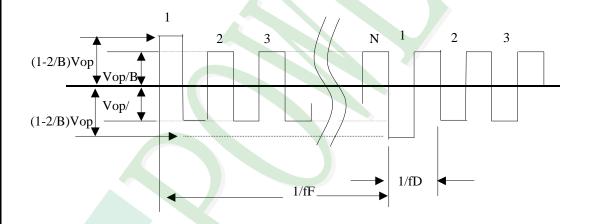
[™] 2 Drive waveform

Vop: Drive voltage fF: Frame frequency 1/B: Bias fD: Drive frequency N: Duty

(1) Selected waveform



(2) Non- Selected wave form

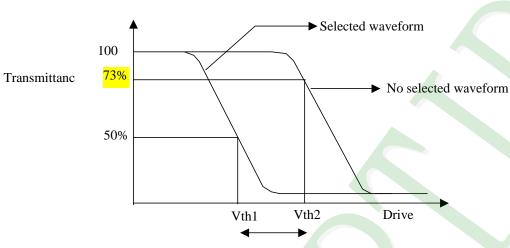


Note:

Frame frequency is defined as follows: Common side supply voltage peak - to - peak /2 = 1 period



Note 3.: Definition of Vth



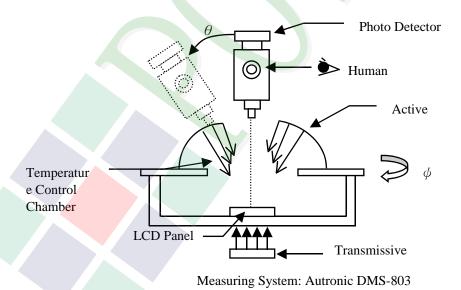
Active voltage range

	Vth1	Vth2
View direction	10°	40 °
Drive waveform	(Selected waveform)	(No selected waveform)
Transmittance	50%	73%

※1 Contrast ratio

= (Brightness in OFF state) / (Brightness in ON state)

Outline of Electro-Optical Characteristics Measuring System





1.6 Backlight Characteristics

LCD Module with LED Backlight

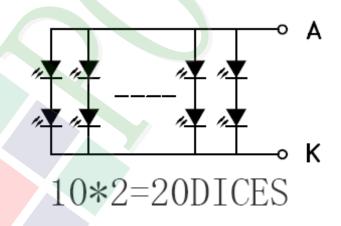
Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
Forward Current	IF	Ta =25°℃	-	150	mA
Reverse Voltage	VR	Ta =25°℃	- 🔥	5	V
Power Dissipation	PD	Ta =25°℃	- ^	690	mW

Electrical / Optical Characteristics

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF	IF=100mA		4.2	4.6	٧
Reverse Current	IR	VR=10V		-	200	uA
Average Brightness (without LCD)	IV	IF=100mA	38	57	-	cd/m ²
Average Brightness (without LCD)	λр	IF=100mA	569	572	576	-
Color			white			

Circuit Diagram:





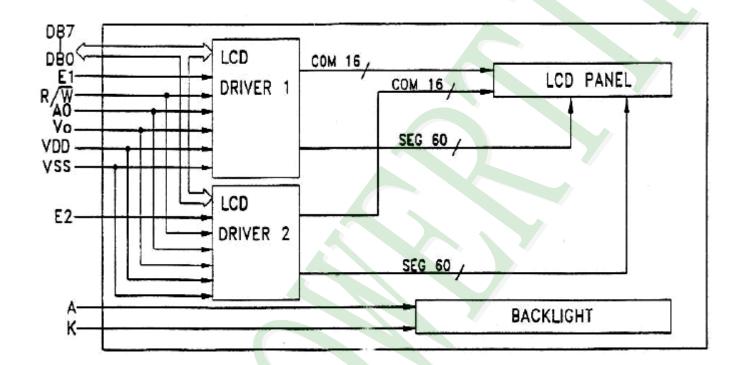
2. MODULE STRUCTURE

2.1 Counter Drawing

2.1.1 LCM Mechanical Diagram

* See Appendix

2.1.2 Block Diagram



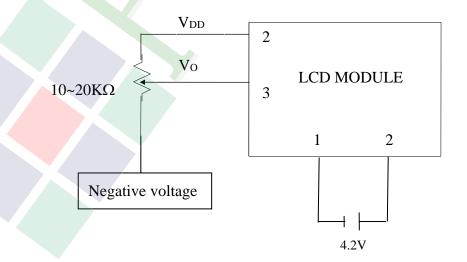




2.2 Interface Pin Description

Pin No	Symbol	Function
1	Vss	Signal ground for LCM and Power supply for LED B/L(-)
2	VDD	Power supply for LCM and Power supply for LED B/L(+)
3	Vo	Contrast adjust
		Register selection input High =Data register
4	A0	Low =Instruction register (for write)
		Busy flag address counter (for read)
5	R/W	R/ W signal input is used to select the read/write mode
		High =Read mode, Low =Write mode
6	E1	Enable Chip IC1
7	E2	Enable Chip IC2
8	NC	No connection.
9	DB0	Data bus line
10	DB1	Data bus line
11	DB2	Data bus line
12	DB3	Data bus line
13	DB4	Data bus line
14	DB5	Data bus line
15	DB6	Data bus line
16	DB7	Data bus line

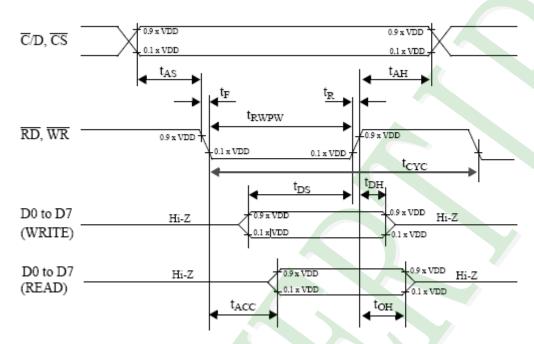
Contrast Adjust





2.3 Timing Characteristics

MPU Bus Read/Write I (80-family MPU)

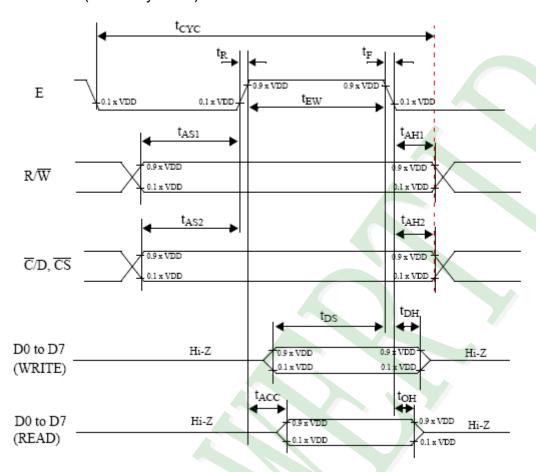


 $V_{DD} = 5 \text{ V} \pm 10\%$; $V_{SS} = 0 \text{ V}$; $T_{amb} = -20 \text{ °C to } +75 \text{ °C}$

symbol	parameter parameter		max.	test conditons	unit
t _{AS}	Address set-up time	20			ns
t _{AH}	Address hold time	10			ns
t _F , t _R	Read/Write pulse falling/rising time		15		ns
t _{RWPW}	Read/Write pulse width	200			ns
t _{cyc}	System cycle time	1000			ns
t _{DS}	Data setup time	80			ns
t _{DH}	Data hold time	10			ns
t _{ACC}	Data READ access time		90	CL= 100 pF.	ns
t _{он}	Data READ output hold time	10	60		ns



MPU Bus Read/Write II (68-family MPU)



 $V_{DD} = 5 \text{ V} \pm 10\%$; $V_{SS} = 0 \text{ V}$; $T_{amb} = -20 \text{ °C to } +75 \text{°C}$.

symbol	parameter	min.	max.	test conditions	unit
t _{AS1}	Address set-up time with respect to R/W	20			ns
t _{AS2}	Address set-up time with respect to C/D, CS	20			ns
t _{AH1}	Address hold time with respect to R/W	10			ns
t _{AH2}	Address hold time respect with to C/D, CS	10			ns
t _F , t _R	Enable (E) pulse falling/rising time		15		ns
tcyc	System cycle time	1000		Note 1	ns
t _{EWR}	Enable pulse width for READ	100			ns
t _{EWW}	Enable pulse width for WRITE	80			ns
t _{DS}	Data setup time	80			ns
t _{DH}	Data hold time	10			ns
tacc	Data access time		90	CL= 100 pF.	ns
toH	Data output hold time	10	60		ns

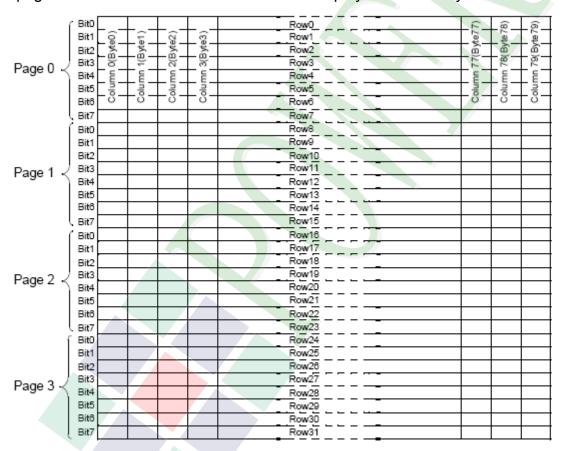


2.4 Display Command

COMMAND	COMMAND CODE								FUNCTION	
COMMAND	D7	D6	D5	D4	D3	D2	D1	D0	FONCTION	
Write Display Data	I	Data to be written into the Display Data Memory.						ata	Write a byte of data to the Display Data Memory.	
Read Display Data	I	Data read from the Display Data Memory.					ta		Read a byte of data from the Display Data Memory.	
Read-Modify-Write	1	1	1	0	0	0	0	0	Start Read-Modify-Write operation.	
END	1 1 1 0 1 1 0			1	0	Stop Read-Modify-Write operation.				
Software Reset	1	1 1 1 0 0 0 1 0				0	1	0	Software Reset.	

2.4.1 Write Display Data

The Write Display Data command writes a byte (8 bits) of data to the Display Data Memory. Data is put on the data bus by the host microcontroller. The location which accepts this byte of data is pointed to by the Page Address Register and the Column Address Register. At the end of the command operation, the content of the Column Address Register is automatically incremented by 1. For page address and column address of the Display Data Memory.



Page/Column allocation of the Display Data Memory

The setting of the control bus for issuing Write Display Data command

C/D	E/(RD)	R/W(WR)
1	1	0



2.4.2 Read Display Data

The Read Display Data command starts a 3-step operation.

- 1. First, the current data of the internal 8-bit output latch of the Display Data Memory is read by the microcontroller, via the 8-bit data bus DB0~DB7.
- 2. Then, a byte of data of the Display Data Memory is transferred to the 8-bit output latch from a location specified by the Page Address Register and the Column Address Register,
- 3. Finally, the content of the Column Address Register is automatically incremented by one. For Display Data Write operation, a dummy write is not needed, because data can be directly written from the data bus to internal memory cells.

Read Display Data

Display Data Memory cell array
(32 row x 80 column)

Column Address Decoder

Read Display Data Memory

The setting of the control bus for issuing Read Display Data command

C/D	E/(RD)	R/W(WR)
1	0	1

2.4.3 Read-Modify-Write

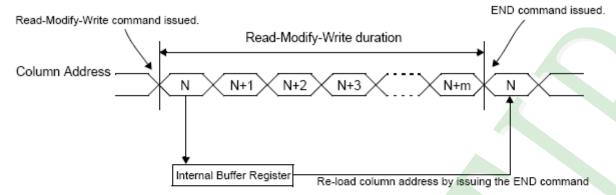
When the Read-Modify-Write command is issued, the SBN1661G_X enters into Read-Modify-Write mode.

In normal operation, when a Read Display Data command or a Write Display Data command is issued, the content of the Column Address Register is automatically incremented by one after the command operation is finished. However, during Read-Modify-Write mode, the content of the Column Address Register is not incremented by one after a Read Display Data command is finished; only the Write Display Data command can make the content of the Column Address Register automatically incremented by one after the command operation is finished.

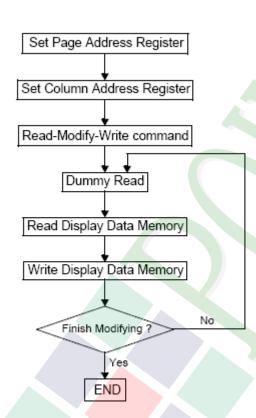
During Read-Modify-Write mode, any other registers, except the Column Address Register, can be



modified. This command is useful when a block of the Display Data Memory needs to be repeatedly read and updated.



Column address change during Read-Modify-Write



The flowchart for Read-Modify-Write

The setting of the control bus for the Read-Modify-Write command

C/D	E/(RD)	R/W(WR)
0	1	0

The setting of the data bus for the Read-Modify-Write command

D7(MSB)	D6	D5	D4	D3	D2	D1	D0(LSB)
1	1	1	0	0	0	0	0



The command code is E0 Hex.

2.4.4 The END command

The END command releases the Read-Modify-Write mode and re-loads the Column Address Register with the value previously stored in the internal buffer (refer to Fig. 17) when the Read-Modify-Write command was issued.

The setting of the control bus for the END command

C/D	E/(RD)	R/W(WR)
0	1	0

The setting of the data bus for the END command

D7(MSB)	D6	D5	D4	D3	D2	D1	D0(LSB)
1	1	1	0	1	1	1	0

The command code is EE Hex.

2.4.5 Software RESET command

The Software Reset command is different from the hardware reset and can not be used to replace hardware reset.

When Software Reset is issued by the host microcontroller,

- the content of the Display Start Line Register is cleared to zero(A4~A0=00000),
- the Page Address Register is set to 3 (A1 A0 = 11),
- the content of the Display Data Memory remains unchanged, and
- the content of all other registers remains unchanged.

The setting of the control bus for Software RESET

C/D	E/(RD)	R/W(WR)
0	1	0

The setting of the data bus for Software RESET

D7(MSB)	D6	D5	D4	D3	D2	D1	D0(LSB)
1	1	1	0	0	0	1	0

The command code is E2 Hex.

2.5 JUMPER

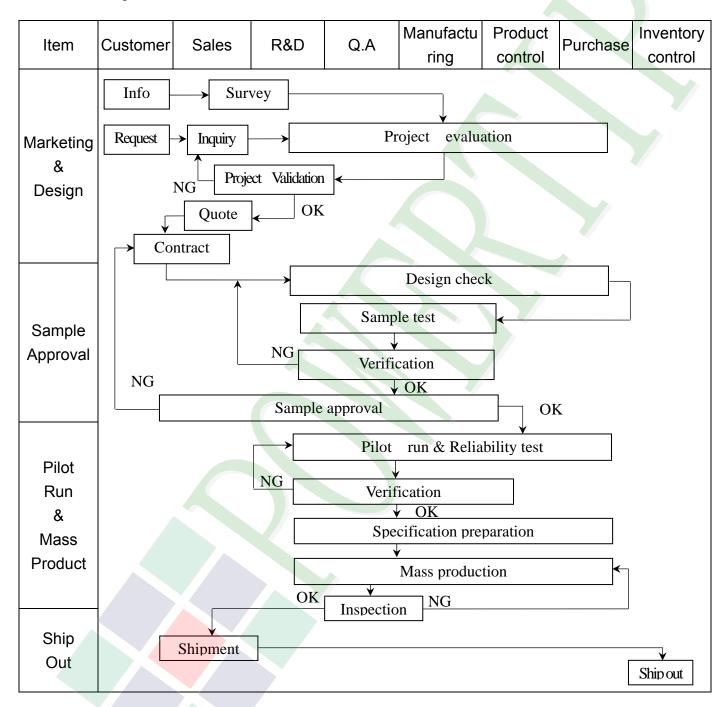
SHORT: J5

OPEN: all the jumper unnoted.

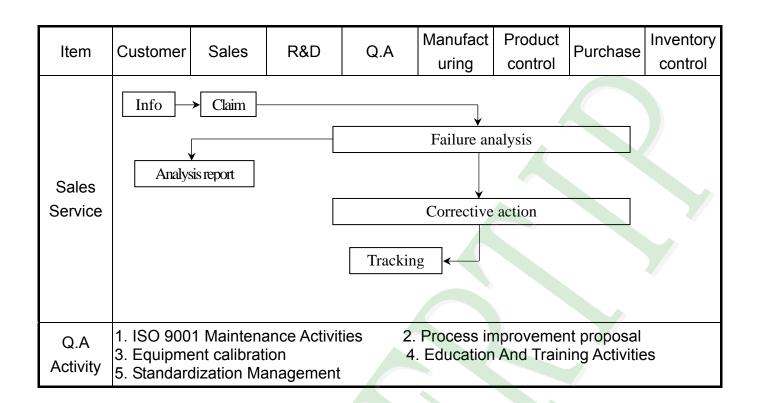


3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart









3.2 Inspection Specification

- ◆Scope: The document shall be applied to LCD Module for Monotype and Color STN(Ver. B01).
- ♦Inspection Standard: MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.
- ◆Equipment : Gauge \ MIL-STD \ Powertip Tester \ Sample
- ◆Defect Level: Major Defect AQL: 0.4 ; Minor Defect: AQL: 1.5.
- **♦**OUT Going Defect Level : Sampling .
- ◆Manner of appearance test :
 - (1). The test be under 20W×2 fluorescent light 'and distance of view must be at 30 cm.
 - (2). Standard of inspection: (Unit: mm)
 - (3). The test direction is base on about around 45° of vertical line. (Fig. 1)
 - (4). Definition of area . (Fig. 2)

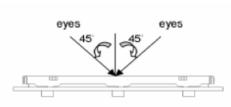


Fig.1

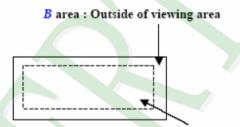


Fig. 2 A area: viewing area

♦ Specification:

NO	Item	Criterion	Level
		1. 1 The part number is inconsistent with work order of Production.	Major
01	Product condition	1. 2 Mixed production types.	Major
		1.3 Assembled in inverse direction.	Major
02	Quantity	2. 1 The quantity is inconsistent with work order of production.	Major
03	Outline dimension	3. 1 Product dimension and structure must conform to Structure diagram.	Major
		4. 1 Missing line character and icon.	Major
		4. 2 No function or no display.	Major
04	Electrical Te <mark>sting</mark>	4, 3 Output data is error.	Major
		4. 4 LCD viewing angle defect.	Major
		4. 5 Current consumption exceeds product specifications.	Major



◆Specification For Monotype and Color STN:

NO	Item	Criterion (Ver				Level	
	Black or white dot \ scratch \ contamination	 5. 1 Round type: 5. 1. 1 display only: • White and black spots on display ≤ 0. 30 mm, no more than 4 white or black spots present. • Densely spaced: NO more than two spots or lines within 3 mm. 					
		5. 1. 2 Non-display :					
	Round type	Dimension (diameter : Φ)		Acceptance			
		$\Phi \leq 0.10$		A area	В	area	
	+ <u>x</u> + ₊	$0.10 < \Phi \le 0.20$	Acce	3			
05	■ Y				1	gnore	Minor
	_	$0.20 < \Phi \leq 0.30$		2		>	
	$\Phi = (x+y)/2$	Total quantity 4					
		5. 1. 3 Line type:					
	T	Dimension Accept		tanc	e (Q'ty)		
	Line type	Length (L) Width (W)		A area		B area	
	o /∳w	W ≤ (Accept no de	dense		
	→ L +	$L \le 3.0$ $0.03 < W \le 0$	0. 05	4		Ignore	
	2	$L \le 2.5$ $0.05 < W \le 0.$	075	-			
		W >0		. 075 As round type			
			I				
		Dimension (diameter : Φ)		Acceptano A area	e (Q	P'ty) B area	
		$\Phi \leq 0.20$		cept no dense		D men	
00	Polarizer	$0.20 < \Phi \leq 0.50$		3			
06	Bubble	$0.20 < \Phi \le 0.30$ $0.50 < \Phi \le 1.00$		2		Ignore	Minor
		$0.50 < \Phi \le 1.00$ $\Phi > 1.00$		0			
		Total quantity		4	\dashv		
		Total quantity		4			



◆Specification For Monotype and Color STN:

NO	Item	Criterion		
		Symbols: X: The length of crack Y: The width of crack. Z: The thickness of crack W: terminal length t: The thickness of glass a: LCD side length		
		7. 1 General glass chip: 7. 1. 1 Chip on panel surface and crack between panels:		
07	The crack of glass	SP SP [NG]	Minor	
		X Y Z		
		≦ a Crack can't enter viewing area ≦1/2 t		
		≤ a Crack can't exceed the half of SP width. 1/2 t < Z ≤2 t		



♦Specification For Monotype and Color STN:

NO	Item	Criterion		
		Symbols: X: The length of crack Z: The thickness of crack t: The thickness of glass 7. 1. 2 Corner crack:		
		X Y Z		
		≤1/5 a Crack can't enter viewing area Z ≤ 1/2 t		
0.7	The crack of			
07	glass	7.2 Protrusion over terminal:	Minor	
		7. 2. 1 Chip on electrode pad:		
		Z X Y Z		
		X		
		X Y Z		
		Front \leq a \leq 1/2 W \leq t		
		Back Neglect		



◆Specification For Monotype and Color STN:

NO	Item	Criterion	Level
		Symbols: X: The length of crack Z: The thickness of crack t: The thickness of glass X: The width of crack W: terminal length a: LCD side length	
		7.2.2 Non-conductive portion:	
07	The crack of glass	X Y Z ≤1/3 a ≤W ≤t O If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode	Minor
		terminal specifications. 7. 2. 3 Glass remain : $\begin{array}{ c c c c c c c c c c c c c c c c c c c$	



◆Specification For Monotype and Color STN:

Speci	meation For Wio	notype and Color STN:	(Ver. B01)
NO	Item	Criterion	Level
	Backlight elements	8. 1 Backlight can't work normally.	Major
08		8. 2 Backlight doesn't light or color is wrong.	Major
		8. 3 Illumination source flickers when lit.	Major
	General appearance	9. 1 Pin type must match type in specification sheet.	Major
		9. 2 No short circuits in components on PCB or FPC.	Major
09		9. 3 Product packaging must the same as specified on packaging specification sheet.	Minor
		9. 4 The folding and peeled off in polarizer are not acceptable.	Minor
		9. 5 The PCB or FPC between B/L assembled distance (PCB or FPC) is ≤1.5 mm.	Minor



4. RELIABILITY TEST

4.1 Reliability Test Condition

NO.	TEST ITEM	TEST CONDITION			
1	High Temperature Storage Test	Keep in 80 ±2°C 240 hrs Surrounding temperature, then storage at normal condition 4hrs.			
2	Low Temperature Storage Test	Keep in-30 ±2℃ 240 hrs Surrounding temperature, then storage at normal condition 4hrs.			
3	High Temperature / High Humidity Storage Test	Keep in +60 $^{\circ}$ C / 90% R.H duration for 240 hrs Surrounding temperature, then storage at normal condition 4hrs. (Excluding the polarizer)			
4	Temperature Cycling Storage Test	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$			
5	ESD Test	Air Discharge: Apply 2 KV with 5 times Discharge for each polarity +/- 1. Temperature ambiance : 15°C ~35°C 2. Humidity relative : 30%~60% 3. Energy Storage Capacitance(Cs+Cd) : 150pF±10% 4. Discharge Resistance(Rd) : 330Ω±10% 5. Discharge, mode of operation : Single Discharge (time between successive discharges at least 1 sec) (Tolerance if the output voltage indication : ±5%)			
6	Vibration Test (Packaged)	1. Sine wave 10 ~ 55 Hz frequency (1 min/sweep) 2. The amplitude of vibration :1.5 mm 3. Each direction (X \ Y \ Z) duration for 2 Hrs			
7	Drop Test (Packaged)	Packing Weight (Kg) Drop Height (cm) 0 ~ 45.4 122 45.4 ~ 90.8 76 90.8 ~ 454 61 Over 454 46 Drop Direction : **1 corner / 3 edges / 6 sides each 1 time			



5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully ,do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is 320±10°C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM.
- 5.2.10 Caution!(LCM products with Capacitive Touch Panel)
 Strong EMI-sources such as switch-mode power supplies (SMPS) can lead to touch malfunction (e.g. ghost-touches).
 Therefore, the touch needs to be thoroughly tested inside the target application.

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is 25°C ±5°C and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

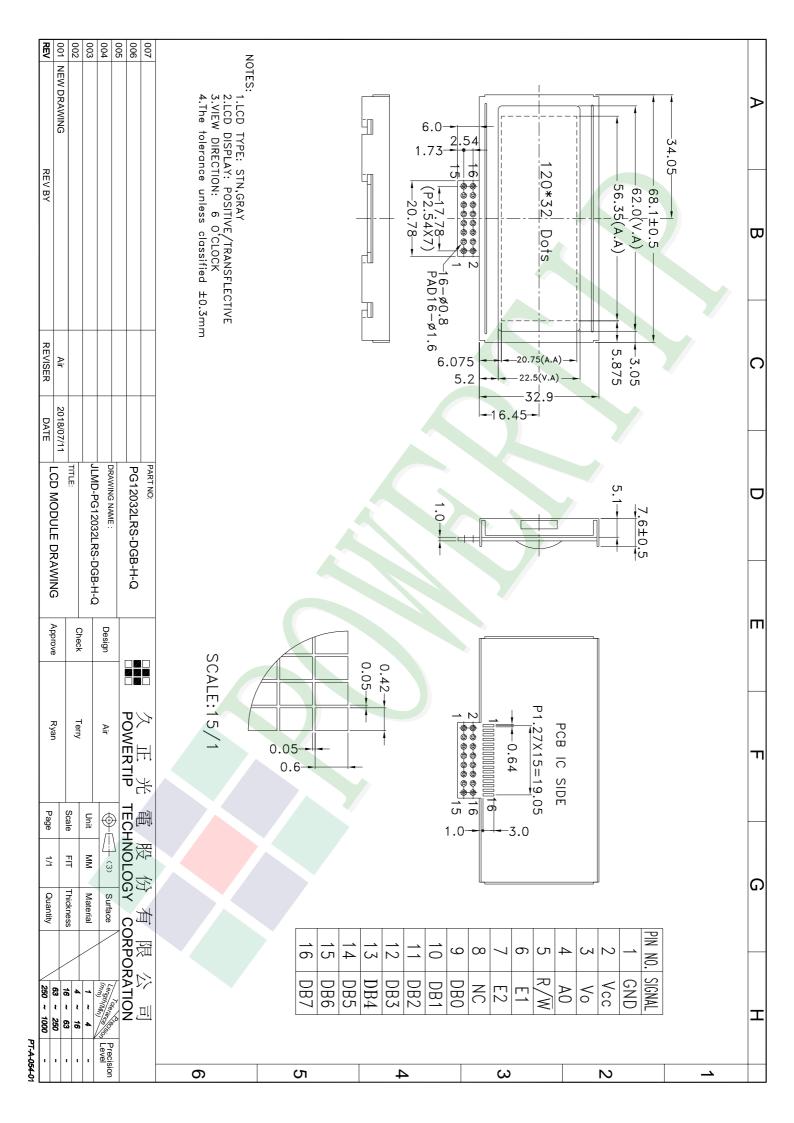
5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security



systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.





Ver.001

Documents NO. JPKG-PG12032LRS-DGB-H-Q

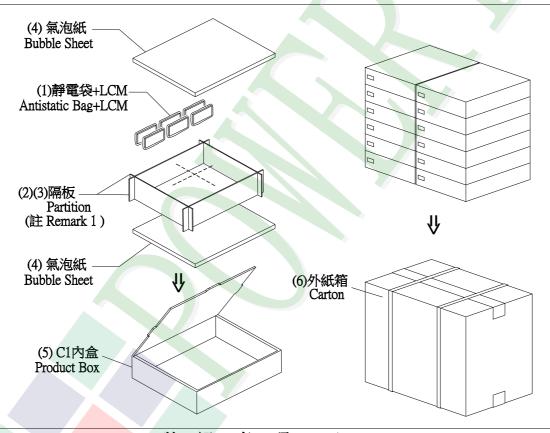
LCM包裝規格書 LCM Packaging Specifications

Approve	Check	Contact
Ryan	Terry	Air

1.包裝材料規格表 (Packaging Material): (per carton)

No.	Item	Model	Dimensions (mm)	1Pcs Weight	Quantity	Total Weight
1	成品 (LCM)	PG12032LRS-DGB-H-Q	68.1 X 32.9 X 7.6	0.0256	468	11.9808
2	靜電袋(1)Antistatic Bag	BAG100100ARABA	100 X 100	0.0011	468	0.5148
3	A1-1隔板(2)A1-1 Partition	BX29500047BZBA	295 X 47 X 3	0.0078	168	1.3104
4	B1-1隔板(3)B1-1 Partition	BX24500047BZBA	245 X 47 X 3	0.0065	48	0.312
5	氣泡紙(4)Bubble Sheet	BAG280240BWABA	280 X 240	0.006	24	0.144
6	C1内盒(5)Product Box	BX31025555AABA	310 X 255 X 55	0.13	12	1.56
7	外紙箱(6)Carton	BX52732536CCBA	527 X 325 X 360	0.83	1	0.83
8						
9						

- 2.一 整箱總重量 (Total LCD Weight in carton): 16.65 Kg±10%
- 3.單箱數量規格表 (Packaging Specifications and Quantity):
 - (1)Quantity Of Spacer: A1-1隔板 X 14, B1-1隔板 X 4
- (2) Total LCM quantity in carton: quantity per box 39 x no of boxes 12 = 468



特記事項(REMARK)

- 1. LCM排放示意圖(前後間隔不放置):
- 1. LCM placed as figure showing:

 (First and last slot should be empty)

